

Search strategies for Case No. 09939073.  
Search done in WEST. Searches done 01/21-  
22/03  
Ex. Andre' Stevenson

USPT

((4411982 )and electrochemical\$2 near (plate\$2  
or plating\$2) near (tool\$2 or device\$2 or  
apparatus\$2) )and (electrolytic\$3 or  
electrochemical\$2 or electrolyte\$2) ) and  
(thick\$2 or thickness\$2) and (test\$2 or testing)

USPT

((4411982 )and electrochemical\$2 near (plate\$2  
or plating\$2) near (tool\$2 or device\$2 or  
apparatus\$2) ) and (electrolytic\$3 or  
electrochemical\$2 or electrolyte\$2)

USPT

(4411982 ) and electrochemical\$2 near (plate\$2  
or plating\$2) near (tool\$2 or device\$2 or  
apparatus\$2)

USPT

4411982

USPT

(6433561 ) and CMP and pad\$2 and speed\$2 and  
pressure\$2

USPT

(6197604 ) and CMP and pad\$2 and speed\$2 and  
pressure\$2

USPT

(5966312 ) and CMP and pad\$2 and speed\$2 and  
pressure\$2

USPT

(6230069 ) and CMP and pad\$2 and speed\$2 and  
pressure\$2ear surface\$2- 6230069 ) and CMP  
and pad\$2 and speed\$2

USPT

(6230069 ) and CMP and pad\$2

USPT

(electrochemical\$2 near (plate\$2 or plating\$2)  
near (tool\$2 or device\$2 or apparatus\$2) ) and  
(thick\$2 or thickness\$2)

USPT

electrochemical\$2 near (plate\$2 or plating\$2)  
near (tool\$2 or device\$2 or apparatus\$2)

USPT

(6433561 ) and bath\$2

USPT

(((((semiconductor\$2  
and (manufacturing or manufacture\$2) and  
(processes or processing) and (tool\$2 or  
workpiece\$2) and (test\$2 or testing) and  
(control\$2 or computer\$2)) )and (electrolytic\$3  
or electrochemical\$2 or electrolyte\$2) )and  
bath\$2 )and (thick\$2 or thickness\$2) ) and  
(electrolytic\$3 or electrochemical\$2 or  
electrolyte\$2) near (tool\$2 or device\$2 or  
apparatus\$2)

USPT

(((((semiconductor\$2 and (manufacturing or  
manufacture\$2) and (processes or processing)  
and (tool\$2 or workpiece\$2) and (test\$2 or  
testing) and (control\$2 or computer\$2)) )and  
(electrolytic\$3 or electrochemical\$2 or  
electrolyte\$2) )and bath\$2 ) and (thick\$2 or  
thickness\$2)

USPT

(((((semiconductor\$2 and (manufacturing or  
manufacture\$2) and (processes or processing)  
and (tool\$2 or workpiece\$2) and (test\$2 or  
testing) and (control\$2 or computer\$2)) )and  
(electrolytic\$3 or electrochemical\$2 or  
electrolyte\$2) ) and bath\$2

USPT

(6433561 ) and (electrolytic\$3 or  
electrochemical\$2 or electrolyte\$2)

USPT

(6197604 ) and (electrolytic\$3 or  
electrochemical\$2 or electrolyte\$2)

USPT

(5966312 ) and (electrolytic\$3 or  
electrochemical\$2 or electrolyte\$2)

USPT

(6230069 ) and (electrolytic\$3 or  
electrochemical\$2 or electrolyte\$2)

USPT

((semiconductor\$2 and (manufacturing or  
manufacture\$2) and (processes or processing)  
and (tool\$2 or workpiece\$2) and (test\$2 or  
testing) and (control\$2 or computer\$2)) )and  
(electrolytic\$3 or electrochemical\$2 or  
electrolyte\$2) ) and CMP and electrochemical\$2  
near (plate\$2 or plating\$2)

USPT

((semiconductor\$2 and (manufacturing or  
manufacture\$2) and (processes or processing)  
and (tool\$2 or workpiece\$2) and (test\$2 or  
testing) and (control\$2 or computer\$2)) ) and  
(electrolytic\$3 or electrochemical\$2 or  
electrolyte\$2)

USPT

(6197604 ) and bath\$2

USPT

(5966312 ) and bath\$2

USPT

(6230069 ) and bath\$2

USPT

(6433561 ) and (electrolytic\$3 or  
electrochemical\$2)

USPT

(6197604 ) and (electrolytic\$3 or  
electrochemical\$2)

USPT

(5966312 ) and (electrolytic\$3 or  
electrochemical\$2)

USPT

(6230069 ) and (electrolytic\$3 or  
electrochemical\$2)

USPT

6433561

USPT

6197604

USPT

5966312

USPT

6230069

USPT

semiconductor\$2 and (processes or processing)  
and (tool\$2 or workpiece\$2) and (test\$2 or  
testing) and (control\$2 or computer\$2) and  
electrochemical\$2 near (plate\$2 or plating\$2)

USPT

(semiconductor\$2 and (manufacturing or  
manufacture\$2) and (processes or processing)  
and (tool\$2 or workpiece\$2) and (test\$2 or  
testing) and (control\$2 or computer\$2) ) and  
CMP and electrochemical\$2 near (plate\$2 or  
plating\$2)

USPT

(6230069 ) and CMP and electrochemical\$2

USPT

(6197604 ) and CMP and electrochemical\$2

USPT

(5966312 ) and CMP and electrochemical\$2

USPT

(5966312 ) and (test\$2 or testing) near  
(workpiece\$2 or tool\$2) and (test\$2 or  
testing)

USPT

(6197604 ) and (test\$2 or testing) near  
(workpiece\$2 or tool\$2) and (test\$2 or testing)

USPT

5966312

USPT

(6230069 ) and (test\$2 or testing)

USPT

(6197604 ) and (test\$2 or testing) near  
(workpiece\$2 or tool\$2)

USPT

6197604

USPT

((semiconductor\$2 and (manufacturing or  
manufacture\$2) and (processes or processing)  
and (tool\$2 or workpiece\$2) and (test\$2 or  
testing) and (control\$2 or computer\$2) )and  
(monitoring or monitor\$2 or controlling) near

(manufacturing or fabrication\$2) ) and (test\$2 or testing) near (workpiece\$2 or tool\$2)

USPT

(6230069 ) and (test\$2 or testing) near (workpiece\$2 or tool\$2)

USPT

6230069

USPT

((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2) )and (etch\$2 or etching) and chamber\$2 and CMP and (plating or plate\$2) ) and (monitoring or monitor\$2 or controlling) near (manufacturing or fabrication\$2)

USPT

(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2) ) and (monitoring or monitor\$2 or controlling) near (manufacturing or fabrication\$2)

USPT

((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2) )and (monitoring or monitor\$2 or controlling) near (manufacturing or fabrication\$2) ) and (etch\$2 or etching) and chamber\$2 and CMP

USPT

(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2) ) and (monitoring or monitor\$2 or controlling) near (manufacturing or fabrication\$2)

USPT

((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2) )and (etch\$2 or etching) and chamber\$2 and CMP and (plating or plate\$2) ) and (monitoring or monitor\$2) near (manufacturing or fabrication\$2)

USPT

((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2) )and (etch\$2 or etching) and chamber\$2 and CMP and (plating or plate\$2) )and pad\$2 ) and (processes or processing) near (tool\$2 or workpiece\$2)

USPT

((semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2) )and (etch\$2 or etching) and chamber\$2 and CMP and (plating or plate\$2) ) and pad\$2

USPT

(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2) ) and (etch\$2 or etching) and chamber\$2 and CMP and (plating or plate\$2)

USPT

(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2) ) and (etch\$2 or etching) and chamber\$2 and CMP (plating or plate\$2)

USPT

(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2) ) and (etch\$2 or etching) and chamber\$2 and CMP and electrochemical\$2 near (plating or plate\$2)

USPT

(semiconductor\$2 and (manufacturing or manufacture\$2) and (processes or processing) and (tool\$2 or workpiece\$2) and (test\$2 or testing) and (control\$2 or computer\$2) ) and (etch\$2 or etching) near chamber\$2 and CMP and electrochemical\$2 near (plating or plate\$2)